

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32L4R9ZIT6	P11A*470XXXY	A	998Z	2017-11-10
	Amount	UoM	Unit type	ST ECOPACK Grade
	1315.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
LQFP	20x20x1.4mm	144		
Comment	Package : 1A LQFP 144 20X20X1.4 2 0099183			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH- 7th July 2017				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration :						Mfr Item Name	P11A*470XXXY				6999999.0	1000000.0
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	25.122	mg	supplier	die	Silicon (Si)	7440-21-3		24.184	mg	962662	18391
				supplier	metallization	Aluminium (Al)	7429-90-5		0.045	mg	1791	34
				supplier	metallization	Copper (Cu)	7440-50-8		0.397	mg	15803	302
				supplier	metallization	Cobalt (Co)	7440-48-4		0.001	mg	40	1
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.129	mg	5135	98
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	199	4
				supplier	metallization	Tungsten (W)	7440-33-7		0.003	mg	119	2
LEADFRAME (MHT - C194)	Copper and its alloy	240.000	mg	supplier	Passivation	Silicon Nitride	12033-89-5		0.101	mg	4020	77
				supplier	Passivation	Silicon Oxide	7631-86-9		0.257	mg	10230	195
				supplier	ALLOY	Copper (Cu)	7440-50-8		233.880	mg	974500	177856
				supplier	ALLOY	Iron (Fe)	7439-89-6		5.760	mg	24000	4380
				supplier	ALLOY	Zinc (Zn)	7440-66-6		0.288	mg	1200	219
LEADFRAME (MHT - Top PPF Plating)	M-011 Other inorganic materials	9.300	mg	supplier	ALLOY	Metallic Phosphorous (P)	7723-14-0		0.072	mg	300	55
				supplier	COATING	Nickel (Ni)	7440-02-0		9.021	mg	970000	6860
				supplier	COATING	Palladium (Pd)	7440-05-3		0.140	mg	15000	106
DIE ATTACH (Sumitomo - CRM-1076Y)	M-011 Other inorganic materials	3.100	mg	supplier	COATING	Gold (Au)	7440-57-5		0.140	mg	15000	106
				supplier	GLUE	Silver(Ag)	7440-22-4		2.170	mg	700000	1650
				supplier	GLUE	Epoxy Resin A	9003-36-5		0.155	mg	50000	118
				supplier	GLUE	Silica fused (SiO2)	7631-86-9		0.310	mg	100000	236
				supplier	GLUE	Dicyandiamide	461-58-5		0.016	mg	5000	12
				supplier	GLUE	Diluent	3101-60-8		0.155	mg	50000	118
				supplier	GLUE	Allyl Compound	Proprietary		0.155	mg	50000	118
BONDING WIRE (IMS Daewon - Au H)	M-011 Other inorganic materials	2.400	mg	supplier	GLUE	Hardener	Proprietary		0.140	mg	45000	106
				supplier	BONDING WIRE	Gold (Au)	7440-57-5		2.376	mg	990050	1807
				supplier	BONDING WIRE	Palladium (Pd)	7440-05-3		0.024	mg	9930	18
				supplier	BONDING WIRE	Silver (Ag)	7440-22-4		0.000	mg	15	0
ENCAPSULATION (Sumitomo - G631H)	M-011 Other inorganic materials	1034.378	mg	supplier	BONDING WIRE	Copper (Cu)	7440-50-8		0.000	mg	5	0
				supplier	MOLDING COMPOUND	Epoxy Resin A	Proprietary		20.706	mg	20000	15746
				supplier	MOLDING COMPOUND	Epoxy Resin B	85954-11-6		41.412	mg	40000	31492
				supplier	MOLDING COMPOUND	Silica Amorphous A	60676-86-0		811.789	mg	785000	617330
				supplier	MOLDING COMPOUND	Silica Amorphous B	7631-86-9		88.001	mg	85000	66921
				supplier	MOLDING COMPOUND	Carbon Black	1333-86-4		5.177	mg	5000	3937
FINISHING - (MHT - Bottom PPF Plating)	M-011 Other inorganic materials	0.700	mg	supplier	MOLDING COMPOUND	Phenol Resin	Proprietary		67.295	mg	65000	51175
				supplier	COATING	Nickel (Ni)	7440-02-0		0.679	mg	970000	516
				supplier	COATING	Palladium (Pd)	7440-05-3		0.011	mg	15000	8
				supplier	COATING	Gold (Au)	7440-57-5		0.011	mg	15000	8